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**Serial Number: 10548316**

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PALM**

**2.) See attached EAST Inventor Search  
Printout shows Inventor search terms**

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 **PALM INTRANET**

## Inventor Information for 10/548316

Inventor Name	City	State/Country
HIROTA, YUSUKE	SAGAMIHARA-SHI	JAPAN
MAKIMURA, HIROO	OTA-KU	JAPAN

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US 20060137319 A1	20060629	Fiber materials having improved qualities required for clothes and method of improving the same	57/210		Hirota; Yusuke et al.
US 20050093180 A1	20050505	Chip scale packaged semiconductor device	257/787	257/737; 257/738; 257/E21.502; 438/127; 438/613	Makimoto, Hirofumi
US 20050035397 A1	20050217	Semiconductor device	257/316	257/E21.685; 257/E27.081	Otoi, Hisakazu et al.
US 20030173656 A1	20030918	Semiconductor device and method of manufacturing the same	257/678	257/E21.502	Makimoto, Hirofumi
US 20030008457 A1	20030109	Semiconductor device and process for same	438/257	257/315; 257/E21.682; 257/E27.103	Makimoto, Hiromi
US 6930351 B2	20050816	Semiconductor device with dummy gate electrode	257/316	257/508; 257/E21.685; 257/E27.081	Otoi; Hisakazu et al.
US 6830958 B2	20041214	Method of making chip scale package	438/110	257/723; 257/778; 257/787; 257/E21.502; 438/108; 438/113; 438/114; 438/126; 438/127; 438/455; 438/458; 438/460; 438/465	Makimoto; Hirofumi
US 6784058 B2	20040831	Process for manufacturing semiconductor	438/264	257/E21.682; 257/E27.103; 438/265	Makimoto; Hiromi

		device including lamp annealing			
US 6489205 B1	20021203	Semiconductor device and method for manufacturing the same	438/297	257/E21.553; 438/440	Makimoto; Hiromi
US 6399422 B1	20020604	Radiating plate structure and method for manufacturing semiconductor devices using the same structure	438/122	257/675; 257/702; 257/706; 257/796; 257/E21.505; 438/106; 438/109; 438/121; 438/125; 438/127	Tomita; Yoshihiro et al.
US 6153493 A	20001128	Method of manufacturing semiconductor device	438/410	257/E21.552; 438/400; 438/404	Makimoto; Hiromi et al.